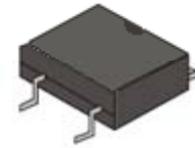


Features

- Glass Passivated Die Construction
- Low Forward Voltage Drop
- High Current Capability
- High Surge Current Capability
- Designed for Surface Mount Application
- Plastic Material – UL Flammability 94V-O



Mechanical Date

- **Case:** ABS, Molded Plastic
- **Terminals:** Plated Leads Solderable per MIL-STD-202, Method 208
- **Polarity:** As Marked on Case
- **Mounting Position:** Any
- **Marking:** Type Number

Major Ratings and Characteristics

I_O	0.8A, 1.0A
V_{RRM}	200 V to 1000 V
I_{FSM}	30 A
I_R	5 μ A
V_F	1.00V
T_j max.	150 °C

Maximum Ratings & Thermal Characteristics ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)

Single Phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

Items	Symbol	ABS2	ABS4	ABS6	ABS8	ABS10	UNIT
Peak Repetitive Reverse Voltage DC Blocking Voltage	V_{RRM} V_{DC}	200	400	600	800	1000	V
RMS Reverse Voltage	$V_{R(RMS)}$	140	280	420	560	700	V
Average Rectified Output Current ⁽¹⁾ Average Rectified Output Current ⁽²⁾	I_O	0.8 1.0					A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load(JEDEC Method)	I_{FSM}	30					A
Current Squared Time	I^2t	3.7					A ² S
Thermal resistance from junction to lead ⁽¹⁾	$R_{\theta JL}$	25					°C/W
Thermal resistance from junction to ambient ⁽¹⁾	$R_{\theta JA}$	80					°C/W
Thermal resistance from junction to ambient ⁽²⁾	$R_{\theta JA}$	62.5					°C/W
Operating junction temperature range	T_J	-55 to +150					°C
Storage temperature range	T_{STG}	-55 to +125					°C

Note 1: Mounted on glass epoxy PC board with 1.3mm² solder pad.

Note 2: Mounted on aluminum substrate PC board with 1.3mm² solder pad.

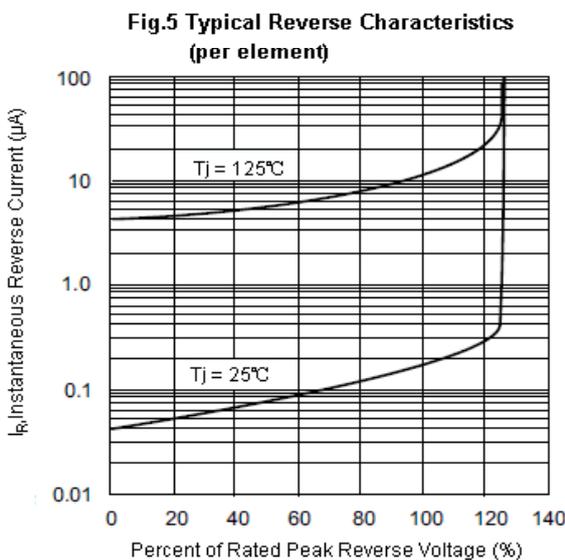
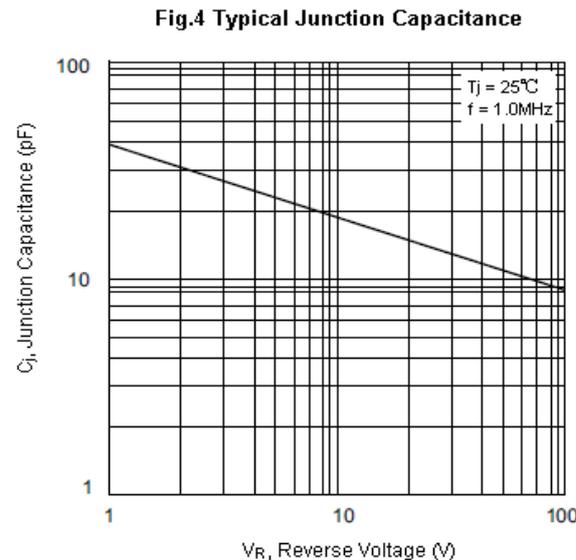
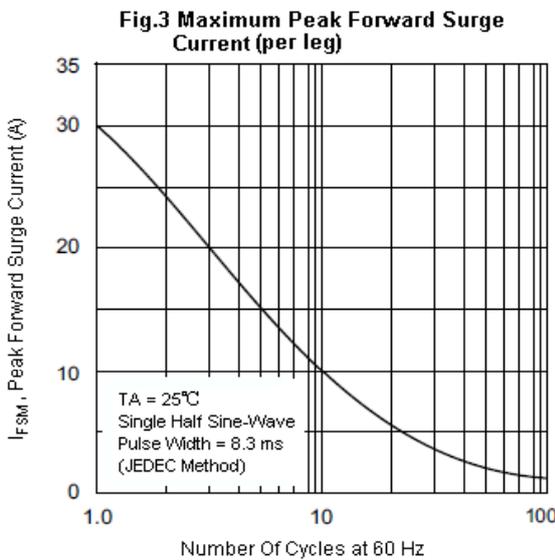
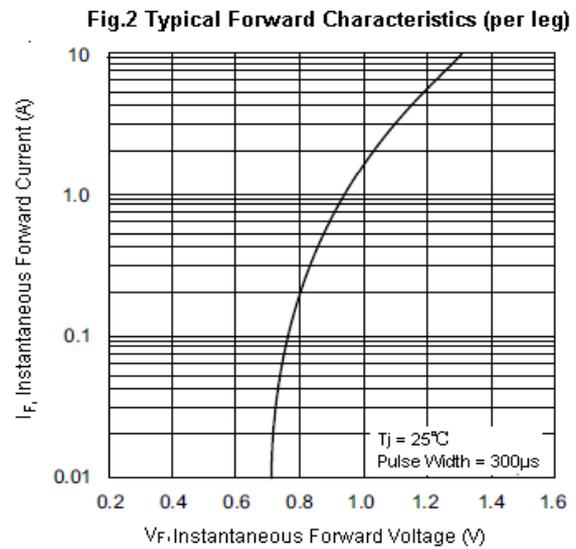
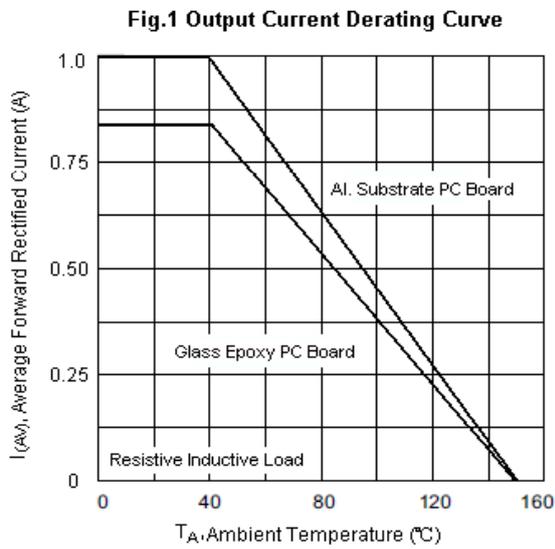
Electrical Characteristics

($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)

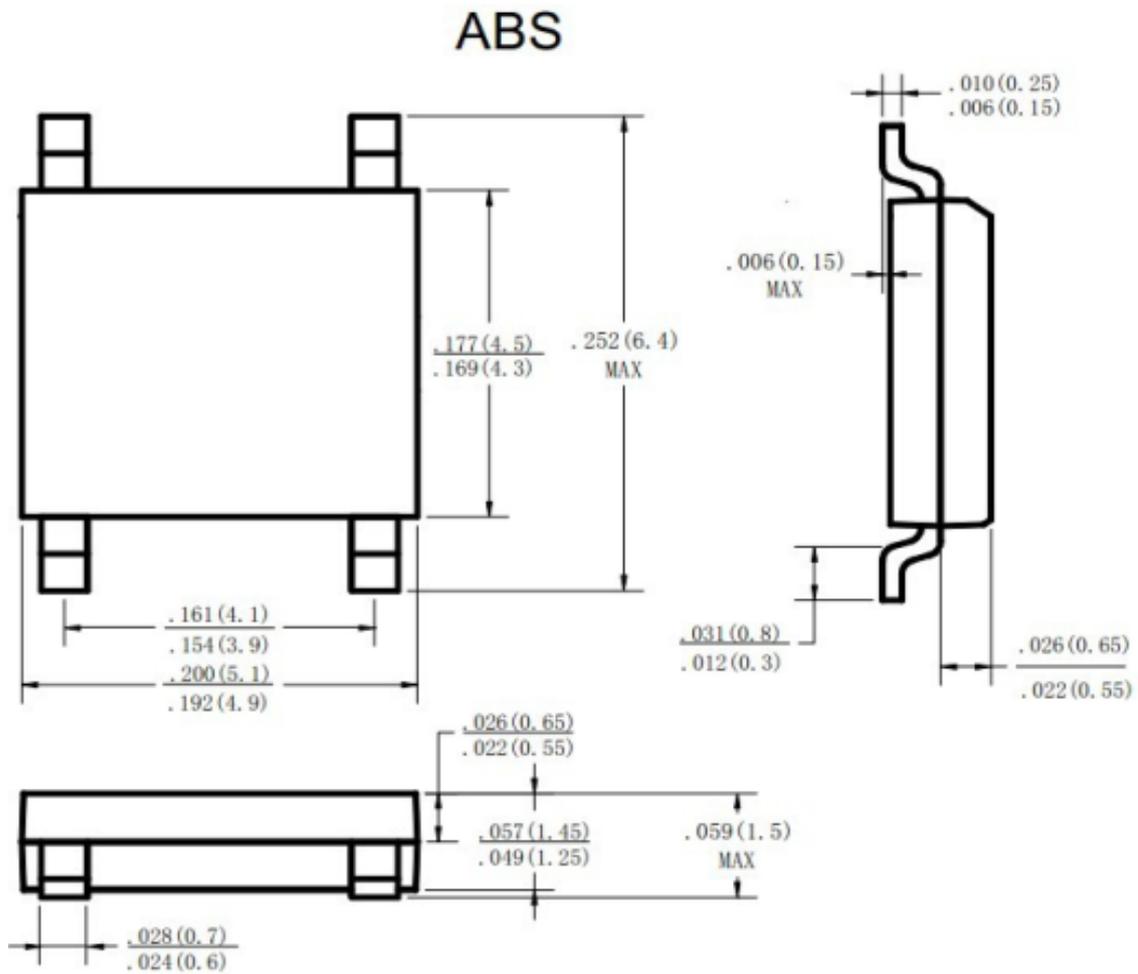
Items	Test conditions	Symbol	Min	Type	Max	UNIT
Instantaneous forward voltage per leg	$I_F = 1.0A^{(3)}$	V_F	-	-	1.00	V
Reverse current	$V_R = V_{DC}$	I_R	-	-	5	μ A
			-	-	500	

Note: 3.Pulse test:300 μ s pulse width,1% duty cycle.

Characteristic Curves ($T_A=25\text{ }^\circ\text{C}$ unless otherwise noted)



Package Outline



Dimensions in inches and (millimeters)